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Application/Control Number: 09/886,593

Art Unit: 2826

## DETAILED ACTION

 Claims 3,6-16, 18, 19, 21, 24,27-34, 36, 37, 39, 41-44, 47, 49-62, 67-79, 81-94 are cancelled

## Allowable Subject Matter

- Claims 1,2,4,5,17,20,22,23,25,26,35,38,40,45,46,48,63-66 and 80 allowed.
- 3. The following is an examiner's statement of reasons for allowance: Prior art failed to establish a stacked multiple-semiconductor die device comprising a plurality of semiconductor dice having similar dimensions each semiconductor die having an active surface including at least four edges and a backside, a field of conductive pads positioned along less than three edges of the active surface of a semiconductor die, the backsides of a first semiconductor die being attached to the surface of the substrate adjacent the at least one conductive bond area of the surface of the substrate and the backside of a second semiconductor die is attached to the active surface of the first semiconductor die in an offset position having the field of conductive bond pads of the first semiconductor die exposed, conductors which connect bond pads of the first semiconductor die to the conductive bond areas of the substrate and conductors which connect bond pads of the second semiconductor die to conductive bond areas of the substrate.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

## Conclusion

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Any inquiry concerning this communication or earlier communications from the examiner should be directed to Fazli Erdem whose telephone number is (703) 305-3868. The examiner can normally be reached on M - F 8:00 - 5:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan Flynn can be reached on (703) 308-6601. The fax phone number for the organization where this application or proceeding is assigned is (703) 308-7722.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

FE November 30, 2003